# **General Purpose Transistor**

## **NPN Silicon**

These transistors are designed for general purpose amplifier applications. They are housed in the SOT-416/SC-75 package which is designed for low power surface mount applications.

#### **Features**

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	75	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	Ic	600	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation (Note 1)  T <sub>A</sub> = 25°C	P <sub>D</sub>	150	mW
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	833	°C/W
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

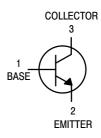
Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.

1



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CASE 463 SOT-416/SC-75 STYLE 1

#### **MARKING DIAGRAM**



1P = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT2222ATT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Chara	ecteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				•	•
Collector – Emitter Breakdown Voltage (N $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	40	_	Vdc	
Collector – Base Breakdown Voltage ( $I_C = 10 \mu Adc, I_E = 0$ )		V <sub>(BR)CBO</sub>	75	-	Vdc
Emitter – Base Breakdown Voltage ( $I_E = 10 \mu Adc, I_C = 0$ )		V <sub>(BR)EBO</sub>	6.0	-	Vdc
Base Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>EB</sub> = 3.0 Vdc)		I <sub>BL</sub>	-	20	nAdc
Collector Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>EB</sub> = 3.0 Vdc)		I <sub>CEX</sub>	-	10	nAdc
ON CHARACTERISTICS (Note 2)					•
DC Current Gain $ \begin{aligned} &(I_C = 0.1 \text{ mAdc, } V_{CE} = 10 \text{ Vdc)} \\ &(I_C = 1.0 \text{ mAdc, } V_{CE} = 10 \text{ Vdc)} \\ &(I_C = 10 \text{ mAdc, } V_{CE} = 10 \text{ Vdc)} \\ &(I_C = 150 \text{ mAdc, } V_{CE} = 10 \text{ Vdc)} \\ &(I_C = 500 \text{ mAdc, } V_{CE} = 10 \text{ Vdc)} \end{aligned} $		H <sub>FE</sub>	35 50 75 100 40	- - - -	_
Collector – Emitter Saturation Voltage ( $I_C = 150 \text{ mAdc}$ , $I_B = 15 \text{ mAdc}$ ) ( $I_C = 500 \text{ mAdc}$ , $I_B = 50 \text{ mAdc}$ )		V <sub>CE(sat)</sub>	- -	0.3 1.0	Vdc
Base – Emitter Saturation Voltage ( $I_C$ = 150 mAdc, $I_B$ = 15 mAdc) ( $I_C$ = 500 mAdc, $I_B$ = 50 mAdc)	V <sub>BE(sat)</sub>	0.6	1.2 2.0	Vdc	
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (I <sub>C</sub> = 20 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 M	ИНz)	f <sub>T</sub>	300	-	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	8.0	pF
Input Capacitance (V <sub>EB</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)		C <sub>ibo</sub>	-	30	pF
Input Impedance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 k	Hz)	h <sub>ie</sub>	0.25	1.25	kΩ
Voltage Feedback Ratio (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 k	h <sub>re</sub>	-	4.0	X 10 <sup>-4</sup>	
Small – Signal Current Gain (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 k	h <sub>fe</sub>	75	375	-	
Output Admittance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 k	h <sub>oe</sub>	25	200	μmhos	
Noise Figure ( $V_{CE}$ = 10 Vdc, $I_{C}$ = 100 $\mu$ Adc, $R_{S}$ = 1.0	NF	-	4.0	dB	
SWITCHING CHARACTERISTICS		l		1	1
Delay Time	(V <sub>CC</sub> = 3.0 Vdc, V <sub>BE</sub> = -0.5 Vdc,	t <sub>d</sub>	_	10	
Rise Time	I <sub>C</sub> = 150 mAdc, I <sub>B1</sub> = 15 mAdc)	t <sub>r</sub>	_	25	ns
Storage Time	(V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc,	t <sub>s</sub>	_	225	
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$	t <sub>f</sub>	_	60	ns

Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.
 Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

#### **SWITCHING TIME EQUIVALENT TEST CIRCUITS**

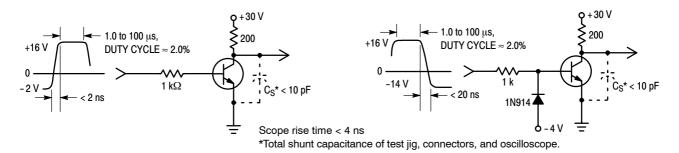


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

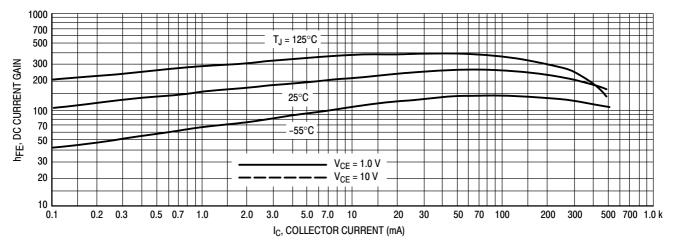


Figure 3. DC Current Gain

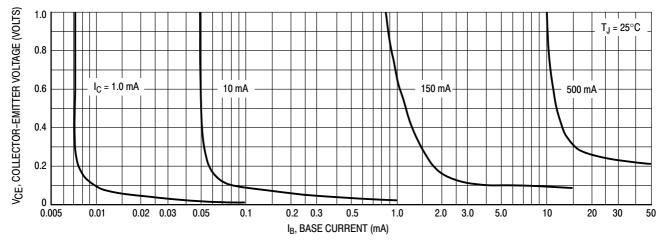


Figure 4. Collector Saturation Region

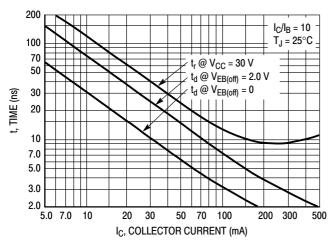


Figure 5. Turn - On Time

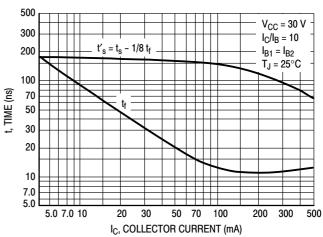


Figure 6. Turn - Off Time

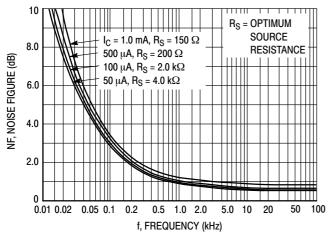


Figure 7. Frequency Effects

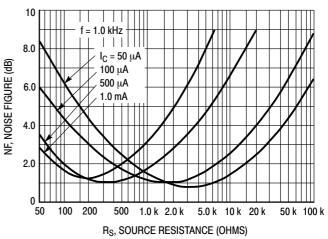


Figure 8. Source Resistance Effects

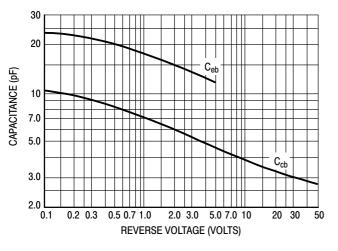


Figure 9. Capacitances

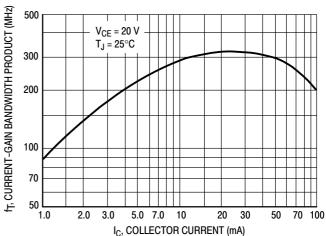


Figure 10. Current-Gain Bandwidth Product

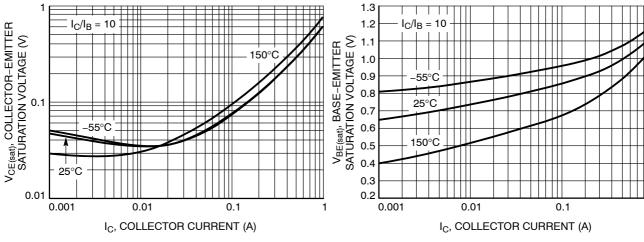


Figure 11. Collector Emitter Saturation Voltage vs. Collector Current

Figure 12. Base Emitter Saturation Voltage vs.
Collector Current

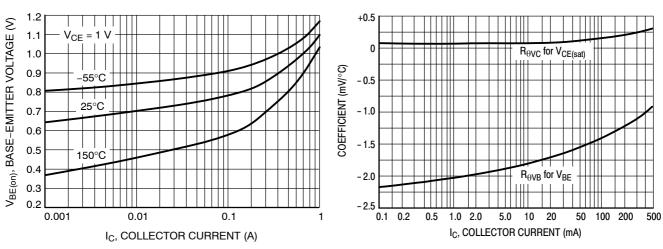


Figure 13. Base Emitter Voltage vs. Collector Current

Figure 14. Temperature Coefficients

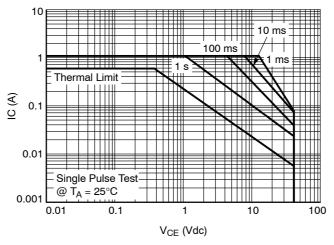
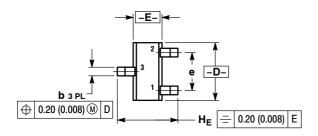
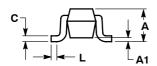


Figure 15. Safe Operating Area

#### PACKAGE DIMENSIONS

SC-75/SOT-416 CASE 463-01 **ISSUE F** 





#### NOTES:

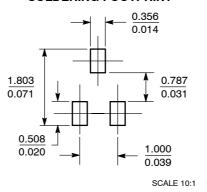
- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS INCHES			;		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.70	0.80	0.90	0.027	0.031	0.035
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.15	0.20	0.30	0.006	0.008	0.012
С	0.10	0.15	0.25	0.004	0.006	0.010
D	1.55	1.60	1.65	0.059	0.063	0.067
Е	0.70	0.80	0.90	0.027	0.031	0.035
е	1.00 BSC			C	0.04 BSC	)
L	0.10	0.15	0.20	0.004	0.006	0.008
He	1.50	1.60	1.70	0.061	0.063	0.065

mm

STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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